



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-06
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
D1060K	TQDP*MQ61B8V	A	ASE WEIHAI	2016-10-06
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TQDP*MQ6188V					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.639	mg	supplier	die	Silicon (Si)	7440-21-3		4.452	mg	959698	13494
				supplier	metallization	Aluminium (Al)	7429-90-5		0.090	mg	19397	273
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	4526	64
				supplier	Passivation	Silicon Oxide	7631-86-9		0.032	mg	6897	97
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	430	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	6681	94
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.011	mg	2371	33
				Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8	
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1400
Soft solder	Solder	4.376	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.179	mg	954982	12662
				supplier	solder	Silver (Ag)	7440-22-4		0.109	mg	24909	330
				supplier	solder	Tin (Sn)	7440-31-5		0.088	mg	20109	267
Bonding wires	Other inorganic materials	0.923	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.923	mg	1000000	2797
Encapsulation	Other Organic Materials	154.073	mg	supplier	mold compound	Fused Silica	60676-86-0		131.732	mg	854997	399188
				supplier	mold compound	Phenol resin Novolak	26834-02-6		7.704	mg	50002	23345
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		7.704	mg	50002	23345
				supplier	mold compound	Poly Phenyl Glycidyl Ether co-Dicyclopentadien	119345-05-0		5.393	mg	35003	16342
				supplier	mold compound	Benzaldehyde hydroxy polymer	106466-55-1		0.770	mg	4998	2333
				supplier	mold compound	Carbon black	1333-86-4		0.770	mg	4998	2333
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167